

APPLICABLE STANDARD							
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾		
	VOLTAGE	50 V AC		STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)		
	CURRENT	0.5 A		OPERATING HUMIDITY RANGE			
SPECIFICATIONS							
ITEM		TEST METHOD		REQUIREMENTS		QT	AT
CONSTRUCTION							
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.		x	x
MARKING		CONFIRMED VISUALLY.				x	x
ELECTRIC CHARACTERISTICS							
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		70 mΩ MAX .		x	—
INSULATION RESISTANCE		100 V DC.		100 MΩ MIN.		x	—
VOLTAGE PROOF		150 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.		x	x
MECHANICAL CHARACTERISTICS							
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 42 N MAX. WITHDRAWAL FORCE: 5.2 N MIN.		x	—
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.		x	—
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 AXIAL DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.		x	—
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 BOTH AXIAL DIRECTIONS.				x	—
ENVIRONMENTAL CHARACTERISTICS							
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.		x	—
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)		② INSULATION RESISTANCE :100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.		x	—
COLD		EXPOSED AT -55°C, 96 h		① CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.		x	—
DRY HEAT		EXPOSED AT 85°C, 96 h		② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.		x	—
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		① NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. ② CONTACT RESISTANCE: VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.		x	—
RESISTANCE TO SOLDERING HEAT		1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.		x	—
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.		x	—
	COUNT	DESCRIPTION OF REVISIONS		DESIGNED		CHECKED	DATE
△							
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. Unless otherwise specified, refer to JIS-C-5402.				APPROVED	HS. OKAWA	12. 03. 06	
				CHECKED	KI. HIROKAWA	12. 03. 06	
				DESIGNED	KT. DOI	12. 03. 02	
				DRAWN	KT. DOI	12. 03. 02	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DRAWING NO.		ELC4-336320-00	
		SPECIFICATION SHEET		PART NO.		FX20-60P-0. 5SV15	
		HIROSE ELECTRIC CO., LTD.		CODE NO.		CL570-1002-3-00 △ 1/1	